

## Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	50	V
Collector-Emitter Voltage	V <sub>CEO</sub>	45	V
Emitter-Base Voltage	V <sub>EBO</sub>	5.0	V
Collector Current	I <sub>C</sub>	0.5	A
Peak Collector Current	I <sub>CM</sub>	1.0	A
Peak Base Current	I <sub>BM</sub>	200	mA

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

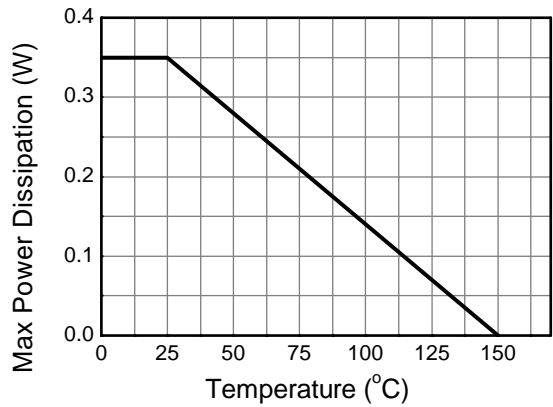
Characteristic	Symbol	Value	Unit
Power Dissipation	P <sub>D</sub>	310	mW
		350	
Thermal Resistance, Junction to Ambient	R <sub>θJA</sub>	403	°C/W
		357	
Thermal Resistance, Junction to Leads	R <sub>θJL</sub>	350	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

## ESD Ratings (Note 9)

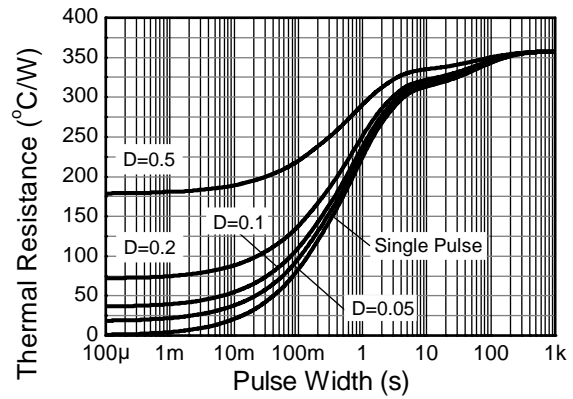
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	8,000	V	3B
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
6. For a device mounted on minimum recommended pad layout FR-4 PCB with high coverage of single sided 1oz copper; device is measured under still air conditions whilst operating in a steady-state.
  7. Same as Note 6, except mounted on 15mm x 15mm 1oz copper.
  8. Thermal resistance from junction to solder-point (at the end of the collector lead).
  9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

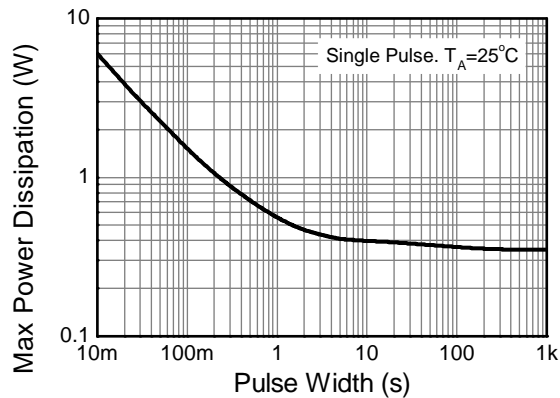
## Thermal Characteristics and Derating Information



**Derating Curve**



**Transient Thermal Impedance**



**Pulse Power Dissipation**

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	50	—	—	V	I <sub>C</sub> = 100μA
Collector-Emitter Breakdown Voltage	BV <sub>CEO</sub>	45	—	—	V	I <sub>C</sub> = 10mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	5	—	—	V	I <sub>C</sub> = 100μA
Collector-Emitter Cut-Off Current	I <sub>CES</sub>	—	—	100 5.0	nA μA	V <sub>CE</sub> = 45V V <sub>CE</sub> = 25V, T <sub>J</sub> = +150°C
Emitter-Base Cut-Off Current	I <sub>EBO</sub>	—	—	100	nA	V <sub>EB</sub> = 5.0V
DC Current Gain (Note 10)	h <sub>FE</sub>	250 170	—	600 —	—	V <sub>CE</sub> = 1.0V, I <sub>C</sub> = 100mA V <sub>CE</sub> = 1.0V, I <sub>C</sub> = 300mA
Collector-Emitter Saturation Voltage (Note 10)	V <sub>CE(SAT)</sub>	—	—	0.7	V	I <sub>C</sub> = 500mA, I <sub>B</sub> = 50mA
Base-Emitter Voltage (Note 10)	V <sub>BE</sub>	—	—	1.2	V	V <sub>CE</sub> = 1.0V, I <sub>C</sub> = 300mA
Gain Bandwidth Product	f <sub>T</sub>	100	—	—	MHz	V <sub>CE</sub> = 5.0V, I <sub>C</sub> = 10mA, f = 50MHz
Collector-Base Capacitance	C <sub>CBO</sub>	—	—	12	pF	V <sub>CB</sub> = 10V, f = 1.0MHz

Note: 10. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

**Typical Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

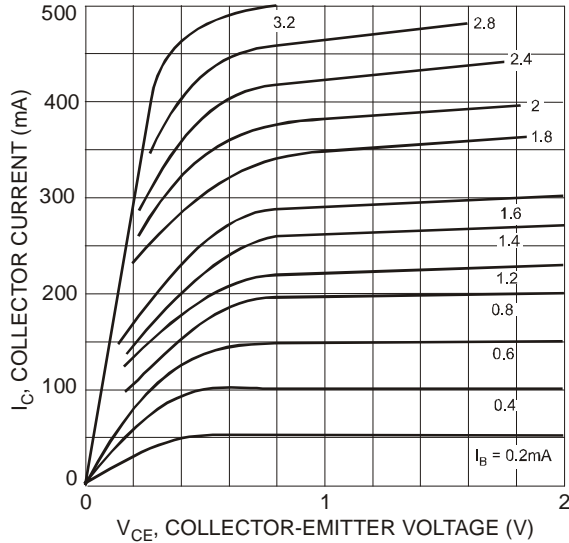


Figure 1 Typical Collector Current vs. Collector-Emitter Voltage

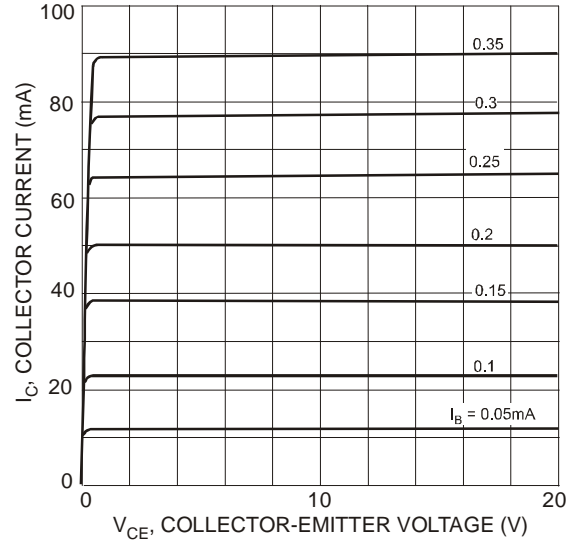


Figure 2 Typical Collector Current vs. Collector-Emitter Voltage

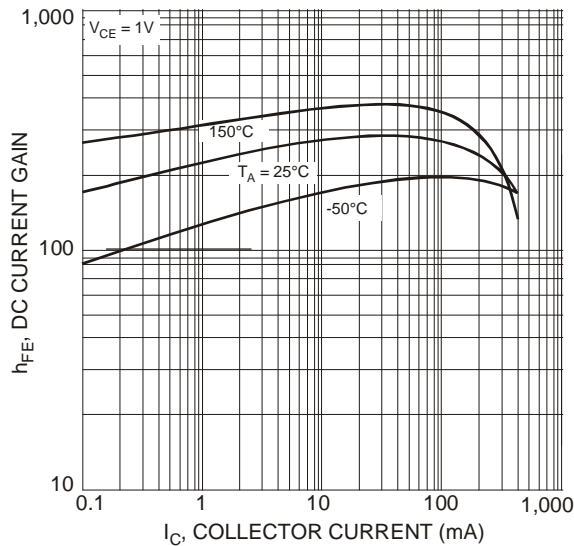


Figure 3 Typical DC Current Gain vs. Collector Current

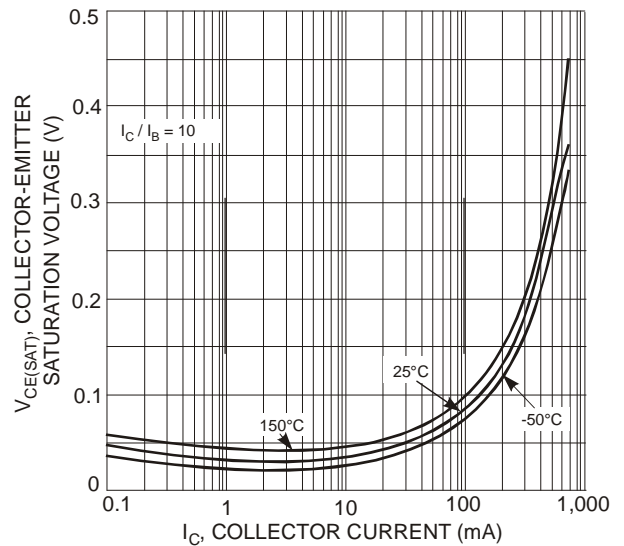


Figure 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

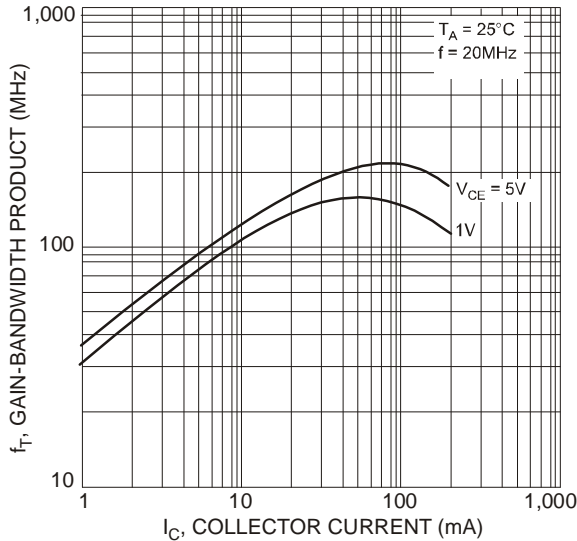
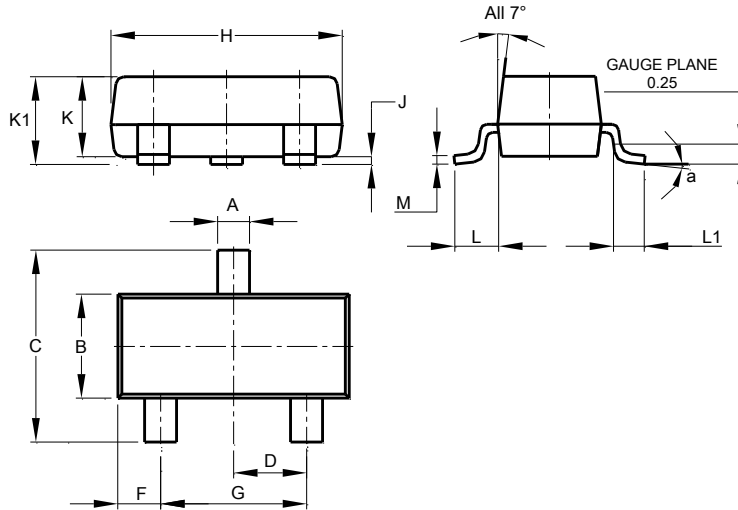


Figure 5 Gain-Bandwidth Product vs. Collector Current

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT23

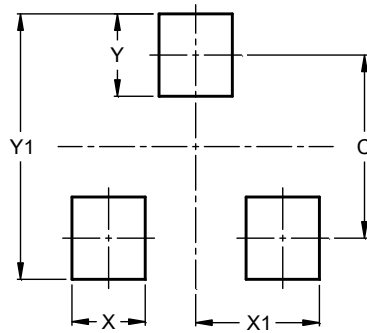


SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	0°	8°	--
All Dimensions in mm			

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT23



Dimensions	Value (in mm)
C	2.0
X	0.8
X1	1.35
Y	0.9
Y1	2.9

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